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Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	10MHz
Connectivity	-
Peripherals	LVD, POR, PWM, WDT
Number of I/O	4
Program Memory Size	4KB (4K × 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.154", 3.90mm Width)
Supplier Device Package	8-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08qd4vsc

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



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Chapter 2 External Signal Description

Although the BKGD pin is a pseudo open-drain pin, the background debug communication protocol provides brief, actively driven, high speedup pulses to ensure fast rise times. Small capacitances from cables and the absolute value of the internal pullup device play almost no role in determining rise and fall times on the BKGD pin.

2.2.5 General-Purpose I/O and Peripheral Ports

The MC9S08QD4 series of MCUs support up to 4 general-purpose I/O pins, 1 input-only pin and 1 output-only pin, which are shared with on-chip peripheral functions (timers, serial I/O, ADC, keyboard interrupts, etc.). On each of the MC9S08QD4 series devices there is one input-only and one output-only port pin.

When a port pin is configured as a general-purpose output or a peripheral uses the port pin as an output, software can select one of two drive strengths and enable or disable slew rate control. When a port pin is configured as a general-purpose input or a peripheral uses the port pin as an input, software can enable a pullup device.

For information about controlling these pins as general-purpose I/O pins, see the Chapter 6, "Parallel Input/Output Control." For information about how and when on-chip peripheral systems use these pins, see the appropriate chapter referenced in Table 2-1.

Immediately after reset, all pins that are not output-only are configured as high-impedance, general-purpose inputs with internal pullup devices disabled. After reset, the output-only port function is not enabled but is configured for low output drive strength with slew rate control enabled. The PTA4 pin defaults to BKGD/MS on any reset.

NOTE

To avoid extra current drain from floating input pins, the reset initialization routine in the application program must either enable on-chip pullup devices or change the direction of unused pins to outputs so the pins do not float.

2.2.5.1 Pin Control Registers

To select drive strength or enable slew rate control or pullup devices, the user writes to the appropriate pin control register located in the high-page register block of the memory map. The pin control registers operate independently of the parallel I/O registers and allow control of a port on an individual pin basis.

2.2.5.1.1 Internal Pullup Enable

An internal pullup device can be enabled for each port pin by setting the corresponding bit in one of the pullup enable registers (PTxPEn). The pullup device is disabled if the pin is configured as an output by the parallel I/O control logic or any shared peripheral function, regardless of the state of the corresponding pullup enable register bit. The pullup device is also disabled if the pin is controlled by an analog function.

The KBI module and IRQ function when enabled for rising edge detection causes an enabled internal pull device to be configured as a pulldown.





Mode	PPDC	CPU, Digital Peripherals, Flash	RAM	ICS	ADC1	Regulator	I/O Pins	RTI
Stop3	0	Standby	Standby	Active	Optionally on	Active	States held	Optionally on

Table 3-2. BD	M Enabled Stop	Mode Behavior
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3.6.4 LVD Enabled in Stop Mode

The LVD system is capable of generating either an interrupt or a reset when the supply voltage drops below the LVD voltage. If the LVD is enabled in stop by setting the LVDE and the LVDSE bits, then the voltage regulator remains active during stop mode. If the user attempts to enter stop2 with the LVD enabled for stop, the MCU will instead enter stop3. Table 3-3 summarizes the behavior of the MCU in stop when the LVD is enabled.

Table 3-3. LVD Enabled Stop Mode Behavior

Mode	PPDC	CPU, Digital Peripherals, Flash	RAM	ICS	ADC1	Regulator	I/O Pins	RTI
Stop3	0	Standby	Standby	Off ¹	Optionally on	Active	States held	Optionally on

¹ ICS can be configured to run in stop3. Please see the ICS registers.

3.6.5 On-Chip Peripheral Modules in Stop Modes

When the MCU enters any stop mode, system clocks to the internal peripheral modules are stopped. Even in the exception case (ENBDM = 1), where clocks to the background debug logic continue to operate, clocks to the peripheral systems are halted to reduce power consumption. Refer to Section 3.6.1, "Stop2 Mode," and Section 3.6.2, "Stop3 Mode," for specific information on system behavior in stop modes.

Poriphoral	Mode				
Fenpheral	Stop2	Stop3			
CPU	Off	Standby			
RAM	Standby	Standby			
Flash	Off	Standby			
Parallel Port Registers	Off	Standby			
ADC1	Off	Optionally On ¹			
ICS	Off	Standby			
TPM1 & TPM2	Off	Standby			
Voltage Regulator	Standby	Standby			
I/O Pins	States Held	States Held			

Table 3-4	Stop	Mode	Behavior
-----------	------	------	-----------------

Requires the asynchronous ADC clock and LVD to be enabled, else in standby.



Aborting a command in this way sets the FACCERR access error flag which must be cleared before starting a new command.

A strictly monitored procedure must be obeyed or the command will not be accepted. This minimizes the possibility of any unintended changes to the flash memory contents. The command complete flag (FCCF) indicates when a command is complete. The command sequence must be completed by clearing FCBEF to launch the command. Figure 4-2 is a flowchart for executing all of the commands except for burst programming. The FCDIV register must be initialized following any reset before using any flash commands.



Figure 4-2. Flash Program and Erase Flowchart

4.5.4 Burst Program Execution

The burst program command is used to program sequential bytes of data in less time than would be required using the standard program command. This is possible because the high voltage to the flash array does not need to be disabled between program operations. Ordinarily, when a program or erase command is issued, an internal charge pump associated with the flash memory must be enabled to supply high voltage to the array. Upon completion of the command, the charge pump is turned off. When a burst



Chapter 4 Memory Map and Register Definition

4.7.5 Flash Status Register (FSTAT)



Figure 4-9. Flash Status Register (FSTAT)

Table 4-12. FSTAT Register Field Descriptions

Field	Description
7 FCBEF	 Flash Command Buffer Empty Flag — The FCBEF bit is used to launch commands. It also indicates that the command buffer is empty so that a new command sequence can be executed when performing burst programming. The FCBEF bit is cleared by writing a 1 to it or when a burst program command is transferred to the array for programming. Only burst program commands can be buffered. 0 Command buffer is full (not ready for additional commands). 1 A new burst program command can be written to the command buffer.
6 FCCF	 Flash Command Complete Flag — FCCF is set automatically when the command buffer is empty and no command is being processed. FCCF is cleared automatically when a new command is started (by writing 1 to FCBEF to register a command). Writing to FCCF has no meaning or effect. 0 Command in progress 1 All commands complete
5 FPVIOL	 Protection Violation Flag — FPVIOL is set automatically when FCBEF is cleared to register a command that attempts to erase or program a location in a protected block (the erroneous command is ignored). FPVIOL is cleared by writing a 1 to FPVIOL. 0 No protection violation. 1 An attempt was made to erase or program a protected location.
4 FACCERR	 Access Error Flag — FACCERR is set automatically when the proper command sequence is not obeyed exactly (the erroneous command is ignored), if a program or erase operation is attempted before the FCDIV register has been initialized, or if the MCU enters stop while a command was in progress. For a more detailed discussion of the exact actions that are considered access errors, see Section 4.5.5, "Access Errors." FACCERR is cleared by writing a 1 to FACCERR. Writing a 0 to FACCERR has no meaning or effect. No access error. An access error has occurred.
2 FBLANK	 Flash Verified as All Blank (erased) Flag — FBLANK is set automatically at the conclusion of a blank check command if the entire flash array was verified to be erased. FBLANK is cleared by clearing FCBEF to write a new valid command. Writing to FBLANK has no meaning or effect. O After a blank check command is completed and FCCF = 1, FBLANK = 0 indicates the flash array is not completely erased. 1 After a blank check command is completed and FCCF = 1, FBLANK = 1 indicates the flash array is completely erased (all 0xFF).



Chapter 5 Resets, Interrupts, and General System Control

5.5.1 Interrupt Stack Frame

Figure 5-1 shows the contents and organization of a stack frame. Before the interrupt, the stack pointer (SP) points at the next available byte location on the stack. The current values of CPU registers are stored on the stack starting with the low-order byte of the program counter (PCL) and ending with the CCR. After stacking, the SP points at the next available location on the stack which is the address that is one less than the address where the CCR was saved. The PC value that is stacked is the address of the instruction in the main program that would have executed next if the interrupt had not occurred.



* High byte (H) of index register is not automatically stacked.

Figure 5-1. Interrupt Stack Frame

When an RTI instruction is executed, these values are recovered from the stack in reverse order. As part of the RTI sequence, the CPU fills the instruction pipeline by reading three bytes of program information, starting from the PC address recovered from the stack.

The status flag causing the interrupt must be acknowledged (cleared) before returning from the ISR. Typically, the flag is cleared at the beginning of the ISR so that if another interrupt is generated by this same source, it will be registered so it can be serviced after completion of the current ISR.

5.5.2 External Interrupt Request (IRQ) Pin

External interrupts are managed by the IRQ status and control register, IRQSC. When the IRQ function is enabled, synchronous logic monitors the pin for edge-only or edge-and-level events. When the MCU is in stop mode and system clocks are shut down, a separate asynchronous path is used so the IRQ (if enabled) can wake the MCU.

5.5.2.1 Pin Configuration Options

The IRQ pin enable (IRQPE) control bit in IRQSC must be 1 in order for the IRQ pin to act as the interrupt request (IRQ) input. As an IRQ input, the user can choose the polarity of edges or levels detected (IRQEDG), whether the pin detects edges-only or edges and levels (IRQMOD), and whether an event causes an interrupt or only sets the IRQF flag which can be polled by software.



Chapter 5 Resets, Interrupts, and General System Control

Reset, Interrupt, and System Control Registers and Control Bits 5.8

One 8-bit register in the direct page register space and eight 8-bit registers in the high-page register space are related to reset and interrupt systems.

Refer to the direct-page register summary in Chapter 3, "Modes of Operation," for the absolute address assignments for all registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

Some control bits in the SOPT1, SOPT2 and SPMSC2 registers are related to modes of operation. Although brief descriptions of these bits are provided here, the related functions are discussed in greater detail in Chapter 3, "Modes of Operation."

5.8.1 Interrupt Pin Request Status and Control Register (IRQSC)

This direct page register includes status and control bits which are used to configure the IRQ function, report status, and acknowledge IRQ events.

_	7	6	5	4	3	2	1	0
R	0	חחפטפו			IRQF	0		
w		IRQPDD	INQEDG			IRQACK	INVIE	
Reset	0	0	0	0	0	0	0	0
		= Unimplemented or Reserved						

Figure 5-2. Interrupt Request Status and Control Register (IRQSC)

	Table 5-3. IRQSC Register Field Descriptions
Field	Description
6 IRQPDD	Interrupt Request (IRQ) Pull Device Disable— This read/write control bit is used to disable the internal pullup/pulldown device when the IRQ pin is enabled (IRQPE = 1) allowing for an external device to be used. 0 IRQ pull device enabled if IRQPE = 1. 1 IRQ pull device disabled if IRQPE = 1.
5 IRQEDG	 Interrupt Request (IRQ) Edge Select — This read/write control bit is used to select the polarity of edges or levels on the IRQ pin that cause IRQF to be set. The IRQMOD control bit determines whether the IRQ pin is sensitive to both edges and levels or only edges. When the IRQ pin is enabled as the IRQ input and is configured to detect rising edges. When IRQEDG = 1 and the internal pull device is enabled, the pullup device is reconfigured as an optional pulldown device. 0 IRQ is falling edge or falling edge/low-level sensitive. 1 IRQ is rising edge or rising edge/high-level sensitive.
4 IRQPE	 IRQ Pin Enable — This read/write control bit enables the IRQ pin function. When this bit is set the IRQ pin can be used as an interrupt request. IRQ pin function is disabled. IRQ pin function is enabled.
3 IRQF	 IRQ Flag — This read-only status bit indicates when an interrupt request event has occurred. 0 No IRQ request. 1 IRQ event detected.

Table 5.9 JDOCO Deviator Field Descriptions



Field	Description
5 LVDIE	 Low-Voltage Detect Interrupt Enable — This bit enables hardware interrupt requests for LVDF. 0 Hardware interrupt disabled (use polling). 1 Request a hardware interrupt when LVDF = 1.
4 LVDRE	 Low-Voltage Detect Reset Enable — This write-once bit enables LVDF events to generate a hardware reset (provided LVDE = 1). 0 LVDF does not generate hardware resets. 1 Force an MCU reset when LVDF = 1.
3 LVDSE	 Low-Voltage Detect Stop Enable — Provided LVDE = 1, this read/write bit determines whether the low-voltage detect function operates when the MCU is in stop mode. 0 Low-voltage detect disabled during stop mode. 1 Low-voltage detect enabled during stop mode.
2 LVDE	 Low-Voltage Detect Enable — This write-once bit enables low-voltage detect logic and qualifies the operation of other bits in this register. 0 LVD logic disabled. 1 LVD logic enabled.
0 BGBE	 Bandgap Buffer Enable — This bit enables an internal buffer for the bandgap voltage reference for use by the ADC module on one of its internal channels. 0 Bandgap buffer disabled. 1 Bandgap buffer enabled.

5.8.9 System Power Management Status and Control 2 Register (SPMSC2)

This high-page register contains status and control bits to configure the stop mode behavior of the MCU. See Section 3.6, "Stop Modes," for more information on stop modes.

	7	6	5	4	3	2	1	0
R	LVWF	0			PPDF	0		
W		LVWACK	LVDV			PPDACK		FFDC
POR:	0 ²	0	0	0	0	0	0	0
LVDR:	0 ²	0	U	U	0	0	0	0
Other Reset	0 ²	0	U	U	0	0	0	0
		= Unimplemer	nted or Reserve	ed	U = Unaffected by reset			

¹ This bit can be written only one time after reset. Additional writes are ignored.

 2 LVWF will be set in the case when V_{supply} transitions below the trip point or after reset and V_{supply} is already below V_{LVW}.

Figure 5-11. System Power Management Status and Control 2 Register (SPMSC2)



Chapter 6 Parallel Input/Output Control



The data direction control bit (PTxDDn) determines whether the output buffer for the associated pin is enabled, and also controls the source for port data register reads. The input buffer for the associated pin is always enabled unless the pin is enabled as an analog function or is an output-only pin.

When a shared digital function is enabled for a pin, the output buffer is controlled by the shared function. However, the data direction register bit will continue to control the source for reads of the port data register.

When a shared analog function is enabled for a pin, both the input and output buffers are disabled. A value of 0 is read for any port data bit where the bit is an input (PTxDDn = 0) and the input buffer is disabled. In general, whenever a pin is shared with both an alternate digital function and an analog function, the analog function has priority such that if both the digital and analog functions are enabled, the analog function controls the pin.

It is a good programming practice to write to the port data register before changing the direction of a port pin to become an output. This ensures that the pin will not be driven momentarily with an old data value that happened to be in the port data register.

6.2 Pin Control — Pullup, Slew Rate and Drive Strength

Associated with the parallel I/O ports is a set of registers located in the high-page register space that operate independently of the parallel I/O registers. These registers are used to control pullups, slew rate and drive strength for the pins.

6.3 Pin Behavior in Stop Modes

Pin behavior following execution of a STOP instruction depends on the stop mode that is entered. An explanation of pin behavior for the various stop modes follows:



- In stop1 mode, all internal registers including parallel I/O control and data registers are powered off. Each of the pins assumes its default reset state (output buffer and internal pullup disabled). Upon exit from stop1, all pins must be re-configured the same as if the MCU had been reset.
- Stop2 mode is a partial power-down mode, whereby latches maintain the pin state as before the STOP instruction was executed. CPU register status and the state of I/O registers must be saved in RAM before the STOP instruction is executed to place the MCU in stop2 mode. Upon recovery from stop2 mode, before accessing any I/O, the user must examine the state of the PPDF bit in the SPMSC2 register. If the PPDF bit is 0, I/O must be initialized as if a power on reset had occurred. If the PPDF bit is 1, I/O data previously stored in RAM, before the STOP instruction was executed, peripherals previously enabled will require being initialized and restored to their pre-stop condition. The user must then write a 1 to the PPDACK bit in the SPMSC2 register. Access of pins is now permitted again in the user's application program.
- In stop3 mode, all pin states are maintained because internal logic stays powered up. Upon recovery, all pin functions are the same as before entering stop3.

6.4 Parallel I/O Registers

6.4.1 Port A Registers

This section provides information about the registers associated with the parallel I/O ports.

Refer to tables in Chapter 4, "Memory Map and Register Definition," for the absolute address assignments for all parallel I/O. This section refers to registers and control bits only by their names. A Freescale Semiconductor-provided equate or header file normally is used to translate these names into the appropriate absolute addresses.

6.4.1.1 Port A Data (PTAD)

_	7	6	5	4	3	2	1	0
R	0	0		ρταη/2	ΡΤΔΟ3	ΡΤΔΟ2	ΡΤΔΟ1	ρταρο
W						I IADZ		I IADO
Reset:	0	0	0	0	0	0	0	0

¹ Reads of bit PTAD5 always return the pin value of PTA5, regardless of the value stored in bit PTADD5.

² Reads of bit PTAD4 always return the contents of PTAD4, regardless of the value stored in bit PTADD4.

Figure 6-2. Port A Data Register (PTAD)



6.4.2.1 Port A Internal Pullup Enable (PTAPE)

An internal pullup device can be enabled for each port pin by setting the corresponding bit in the pullup enable register (PTAPEn). The pullup device is disabled if the pin is configured as an output by the parallel I/O control logic or any shared peripheral function regardless of the state of the corresponding pullup enable register bit. The pullup device is also disabled if the pin is controlled by an analog function.

_	7	6	5	4	3	2	1	0
R	0	0		ρτάρεμ1	ρτάρες	ΡΤΔΡΕ2		ρτάρεο
W								
Reset:	0	0	0	0	0	0	0	0

¹ PTAPE4 has no effect on the output-only PTA4 pin.

Figure 6-4. Internal Pullup Enable for Port A Register (PTAPE)

Table 6-3. PTAPE Register Field Descriptions

Field	Description
5:0	Internal Pullup Enable for Port A Bits — Each of these control bits determines if the internal pullup device is
PTAPE[5:0]	enabled for the associated PTA pin. For port A pins that are configured as outputs, these bits have no effect and
	the internal pullup devices are disabled.
	0 Internal pullup device disabled for port A bit n.
	1 Internal pullup device enabled for port A bit n.

6.4.2.2 Port A Slew Rate Enable (PTASE)

Slew rate control can be enabled for each port pin by setting the corresponding bit in the slew rate control register (PTASEn). When enabled, slew control limits the rate at which an output can transition in order to reduce EMC emissions. Slew rate control has no effect on pins which are configured as inputs.

	7	6	5	4	3	2	1	0
R	0	0		DTAGEA	DTAGES	DTAGE2		DTASEO
w			T IAGES		TIAGES	TIAGEZ	TIAGET	I IAGEO
Reset:	0	0	1	1	1	1	1	1

¹ PTASE5 has no effect on the input-only PTA5 pin.

Figure 6-5. Slew Rate Enable for Port A Register (PTASE)

Table 6-4. PTASE Register Field Descriptions

Field	Description
5:0 PTASE[5:0]	 Output Slew Rate Enable for Port A Bits — Each of these control bits determines if the output slew rate control is enabled for the associated PTA pin. For port A pins that are configured as inputs, these bits have no effect. Output slew rate control disabled for port A bit n. Output slew rate control enabled for port A bit n.

MC9S08QD4 Series MCU Data Sheet, Rev. 6



Source Form	Operation	dress			Cyc-by-Cyc Details	Affect on CCR		
		Add Moc		Cyc		VH	INZC	
RSP	Reset Stack Pointer (Low Byte) SPL ← \$FF (High Byte Not Affected)	INH	90	1	q			
RTI	Return from Interrupt SP ← (SP) + \$0001; Pull (CCR) SP ← (SP) + \$0001; Pull (A) SP ← (SP) + \$0001; Pull (X) SP ← (SP) + \$0001; Pull (PCH) SP ← (SP) + \$0001; Pull (PCL)	INH	80	9	սսսսեքքք	11	\$\$\$	
RTS	Return from Subroutine SP \leftarrow SP + \$0001; Pull (PCH) SP \leftarrow SP + \$0001; Pull (PCL)	INH	81	5	ufppp			
SBC #opr8i SBC opr8a SBC opr16a SBC oprx16,X SBC oprx8,X SBC ,X SBC oprx16,SP SBC oprx8,SP	Subtract with Carry A \leftarrow (A) – (M) – (C)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A2 ii B2 dd C2 hh 11 D2 ee ff E2 ff F2 9E D2 ee ff 9E E2 ff	2 3 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	↓ -	-\$\$\$	
SEC	Set Carry Bit $(C \leftarrow 1)$	INH	99	1	q		1	
SEI	Set Interrupt Mask Bit $(I \leftarrow 1)$	INH	9B	1	q		1 – – –	
STA opr8a STA opr16a STA oprx16,X STA oprx8,X STA ,X STA oprx16,SP STA oprx8,SP	Store Accumulator in Memory M ← (A)	DIR EXT IX2 IX1 IX SP2 SP1	B7 dd C7 hh ll D7 ee ff E7 ff F7 9E D7 ee ff 9E E7 ff	3 4 3 2 5 4	wpp pwpp pwpp pwpp	0 –	- \$ \$ -	
STHX opr8a STHX opr16a STHX oprx8,SP	Store H:X (Index Reg.) (M:M + \$0001) ← (H:X)	DIR EXT SP1	35 dd 96 hh ll 9E FF ff	4 5 5	ммър рммър рммър	0 –	-\$\$-	
STOP	Enable Interrupts: Stop Processing Refer to MCU Documentation I bit \leftarrow 0; Stop Processing	INH	8E	2	fp		0	
STX opr8a STX opr16a STX oprx16,X STX oprx8,X STX ,X STX oprx16,SP STX oprx8,SP	Store X (Low 8 Bits of Index Register) in Memory $M \leftarrow (X)$	DIR EXT IX2 IX1 IX SP2 SP1	BF dd CF hh ll DF ee ff EF ff FF 9E DF ee ff 9E EF ff	3 4 3 2 5 4	mbb bmbb pmbb pmbb	0 –	- \$ \$ -	



Bit-Man	pulation	Branch		Rea	d-Modify-W	/rite	•	Cor	ntrol	,		Register	/Memory		
00 5	10 5	20 3	30 5	40 1	50 1	60 5	70 4	80 9	90 3	A0 2	B0 3	C0 4	D0 4	E0 3	F0 3
BRSET0	BSET0	BRA	NEG	NEGA	NEGX	NEG	NEG	RTI	BGE	SUB	SUB	SUB	SUB	SUB	SUB
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	2 REL	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
01 5	11 5	21 3	31 5	41 4	51 4	61 5	71 5	81 6	91 3	A1 2	B1 3	C1 4	D1 4	E1 3	F1 3
BRCLR0	BCLR0	BRN	CBEQ	CBEQA	CBEQX	CBEQ	CBEQ	RTS	BLT	CMP	CMP	CMP	CMP	CMP	CMP
3 DIR	2 DIR	2 REL	3 DIR	3 IMM	3 IMM	3 IX1+	2 IX+	1 INH	2 REL	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
02 5	12 5	22 3	32 5	42 5	52 6	62 1	72 1	82 5+	92 3	A2 2	B2 3	C2 4	D2 4	E2 3	F2 3
BRSET1	BSET1	BHI	LDHX	MUL	DIV	NSA	DAA	BGND	BGT	SBC	SBC	SBC	SBC	SBC	SBC
3 DIR	2 DIR	2 REL	3 EXT	1 INH	1 INH	1 INH	1 INH	1 INH	2 REL	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
03 5	13 5	23 3	33 5	43 1	53 1	63 5	73 4	83 11	93 3	A3 2	B3 3	C3 4	D3 4	E3 3	F3 3
BRCLR1	BCLR1	BLS	COM	COMA	COMX	COM	COM	SWI	BLE	CPX	CPX	CPX	CPX	CPX	CPX
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	2 REL	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
04 5	14 5	24 3	34 5	44 1	54 1	64 5	74 4	84 1	94 2	A4 2	B4 3	C4 4	D4 4	E4 3	F4 3
BRSET2	BSET2	BCC	LSR	LSRA	LSRX	LSR	LSR	TAP	TXS	AND	AND	AND	AND	AND	AND
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
05 5	15 5	25 3	35 4	45 3	55 4	65 3	75 5	85 1	95 2	A5 2	B5 3	C5 4	D5 4	E5 3	F5 3
BRCLR2	BCLR2	BCS	STHX	LDHX	LDHX	CPHX	CPHX	TPA	TSX	BIT	BIT	BIT	BIT	BIT	BIT
3 DIR	2 DIR	2 REL	2 DIR	3 IMM	2 DIR	3 IMM	2 DIR	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
06 5	16 5	26 3	36 5	46 1	56 1	66 5	76 4	86 3	96 5	A6 2	B6 3	C6 4	D6 4	E6 3	F6 3
BRSET3	BSET3	BNE	ROR	RORA	RORX	ROR	ROR	PULA	STHX	LDA	LDA	LDA	LDA	LDA	LDA
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	3 EXT	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
07 5	17 5	27 3	37 5	47 1	57 1	67 5	77 4	87 2	97 1	A7 2	B7 3	C7 4	D7 4	E7 3	F7 2
BRCLR3	BCLR3	BEQ	ASR	ASRA	ASRX	ASR	ASR	PSHA	TAX	AIS	STA	STA	STA	STA	STA
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
08 5	18 5	28 3	38 5	48 1	58 1	68 5	78 4	88 3	98 1	A8 2	B8 3	C8 4	D8 4	E8 3	F8 3
BRSET4	BSET4	BHCC	LSL	LSLA	LSLX	LSL	LSL	PULX	CLC	EOR	EOR	EOR	EOR	EOR	EOR
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
09 5	19 5	29 3	39 5	49 1	59 1	69 5	79 4	89 2	99 1	A9 2	B9 3	C9 4	D9 4	E9 3	F9 3
BRCLR4	BCLR4	BHCS	ROL	ROLA	ROLX	ROL	ROL	PSHX	SEC	ADC	ADC	ADC	ADC	ADC	ADC
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
0A 5	1A 5	2A 3	3A 5	4A 1	5A 1	6A 5	7A 4	8A 3	9A 1	AA 2	BA 3	CA 4	DA 4	EA 3	FA 3
BRSET5	BSET5	BPL	DEC	DECA	DECX	DEC	DEC	PULH	CLI	ORA	ORA	ORA	ORA	ORA	ORA
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
0B 5	1B 5	2B 3	3B 7	4B 4	5B 4	6B 7	7B 6	8B 2	9B 1	AB 2	BB 3	CB 4	DB 4	EB 3	FB 3
BRCLR5	BCLR5	BMI	DBNZ	DBNZA	DBNZX	DBNZ	DBNZ	PSHH	SEI	ADD	ADD	ADD	ADD	ADD	ADD
3 DIR	2 DIR	2 REL	3 DIR	2 INH	2 INH	3 IX1	2 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
0C 5	1C 5	2C 3	3C 5	4C 1	5C 1	6C 5	7C 4	8C 1	9C 1		BC 3	CC 4	DC 4	EC 3	FC 3
BRSET6	BSET6	BMC	INC	INCA	INCX	INC	INC	CLRH	RSP		JMP	JMP	JMP	JMP	JMP
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH		2 DIR	3 EXT	3 IX2	2 IX1	1 IX
0D 5	1D 5	2D 3	3D 4	4D 1	5D 1	6D 4	7D 3		9D 1	AD 5	BD 5	CD 6	DD 6	ED 5	FD 5
BRCLR6	BCLR6	BMS	TST	TSTA	TSTX	TST	TST		NOP	BSR	JSR	JSR	JSR	JSR	JSR
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX		1 INH	2 REL	2 DIR	3 EXT	3 IX2	2 IX1	1 IX
0E 5 BRSET7 3 DIR	1E 5 BSET7 2 DIR	2E 3 BIL 2 REL	3E 6 CPHX 3 EXT	4E 5 MOV 3 DD	5E 5 MOV 2 DIX+	6E 4 MOV 3 IMD	7E 5 MOV 2 IX+D	8E 2+ STOP 1 INH	9E Page 2	AE 2 LDX 2 IMM	BE 3 LDX 2 DIR	CE 4 LDX 3 EXT	DE 4 LDX 3 IX2	EE 3 LDX 2 IX1	FE 3 LDX 1 IX
0F 5	1F 5	2F 3	3F 5	4F 1	5F 1	6F 5	7F 4	8F 2+	9F 1	AF 2	BF 3	CF 4	DF 4	EF 3	FF 2
BRCLR7	BCLR7	BIH	CLR	CLRA	CLRX	CLR	CLR	WAIT	TXA	AIX	STX	STX	STX	STX	STX
3 DIR	2 DIR	2 REL	2 DIR	1 INH	1 INH	2 IX1	1 IX	1 INH	1 INH	2 IMM	2 DIR	3 EXT	3 IX2	2 IX1	1 IX

Table 7-3, C)pcode Ma	p (Sheet	1 of 2)
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INH	Inherent
IMM	Immediate
DIR	Direct
EXT	Extended
DD	DIR to DIR
IX+D	IX+ to DIR

REL IX IX1 IX2 IMD DIX+ Relative Indexed, No Offset Indexed, 8-Bit Offset Indexed, 16-Bit Offset IMM to DIR DIR to IX+

SP1 SP2 IX+

Stack Pointer, 8-Bit Offset Stack Pointer, 16-Bit Offset Indexed, No Offset with Post Increment Indexed, 1-Byte Offset with Post Increment IX1+

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Opcode in Hexadecimal F0 3 SUB Instruction Mnemonic 1 IX Addressing Mode Number of Bytes 1



Chapter 8 Analog-to-Digital Converter (ADC10V1)

The RTI can be configured to cause a hardware trigger in MCU run, wait, and stop3.

8.1.1.4 Analog Pin Enables

The ADC on MC9S08QD4 contains only one analog pin enable register, APCTL1.

8.1.1.5 Temperature Sensor

To use the on-chip temperature sensor, the user must perform the following:

- Configure ADC for long sample with a maximum of 1 MHz clock
- Convert the bandgap voltage reference channel (AD27)
 - By converting the digital value of the bandgap voltage reference channel using the value of V_{BG} the user can determine V_{DD}. For value of bandgap voltage, see Appendix A.5, "DC Characteristics".
- Convert the temperature sensor channel (AD26)
 - By using the calculated value of V_{DD} , convert the digital value of AD26 into a voltage, V_{TEMP}

Equation 8-1 provides an approximate transfer function of the on-chip temperature sensor for $V_{DD} = 3.0V$, Temp = 25°C, using the ADC at $f_{ADCK} = 1.0$ MHz and configured for long sample.

0.0017 is the uncalibrated voltage versus temperature slope in V/°C. Uncalibrated accuracy of the temperature sensor is approximately $\pm 12^{\circ}$ C, using Equation 8-1.

To improve accuracy the user must calibrate the bandgap voltage reference and temperature sensor.

Calibrating at 25°C will improve accuracy to ± 4.5 °C.

Calibration at 3 points, -40°C, 25°C and 105°C will improve accuracy to ± 2.5 °C. Once calibration has been completed, the user will need to calculate the slope for both hot and cold. In application code, the user would then calculate the temperature using Equation 8-1 as detailed above and then determine if the temperature is above or below 25°C. Once determined if the temperature is above or below 25°C, the user can recalculate the temperature using the hot or cold slope value obtained during calibration.

8.1.1.6 Low-Power Mode Operation

The ADC is capable of running in stop3 mode but requires LVDSE in SPMSC1 to be set.



8.1.2 Features

Features of the ADC module include:

- Linear successive approximation algorithm with 10 bits resolution.
- Up to 28 analog inputs.
- Output formatted in 10- or 8-bit right-justified format.
- Single or continuous conversion (automatic return to idle after single conversion).
- Configurable sample time and conversion speed/power.
- Conversion complete flag and interrupt.
- Input clock selectable from up to four sources.
- Operation in wait or stop3 modes for lower noise operation.
- Asynchronous clock source for lower noise operation.
- Selectable asynchronous hardware conversion trigger.
- Automatic compare with interrupt for less-than, or greater-than or equal-to, programmable value.

8.1.3 Block Diagram

Figure 8-2 provides a block diagram of the ADC module



Analog-to-Digital Converter (S08ADC10V1)

8.4.4.2 Completing Conversions

A conversion is completed when the result of the conversion is transferred into the data result registers, ADCRH and ADCRL. This is indicated by the setting of COCO. An interrupt is generated if AIEN is high at the time that COCO is set.

A blocking mechanism prevents a new result from overwriting previous data in ADCRH and ADCRL if the previous data is in the process of being read while in 10-bit MODE (the ADCRH register has been read but the ADCRL register has not). When blocking is active, the data transfer is blocked, COCO is not set, and the new result is lost. In the case of single conversions with the compare function enabled and the compare condition false, blocking has no effect and ADC operation is terminated. In all other cases of operation, when a data transfer is blocked, another conversion is initiated regardless of the state of ADCO (single or continuous conversions enabled).

If single conversions are enabled, the blocking mechanism could result in several discarded conversions and excess power consumption. To avoid this issue, the data registers must not be read after initiating a single conversion until the conversion completes.

8.4.4.3 Aborting Conversions

Any conversion in progress will be aborted when:

- A write to ADCSC1 occurs (the current conversion will be aborted and a new conversion will be initiated, if ADCH are not all 1s).
- A write to ADCSC2, ADCCFG, ADCCVH, or ADCCVL occurs. This indicates a mode of operation change has occurred and the current conversion is therefore invalid.
- The MCU is reset.
- The MCU enters stop mode with ADACK not enabled.

When a conversion is aborted, the contents of the data registers, ADCRH and ADCRL, are not altered but continue to be the values transferred after the completion of the last successful conversion. In the case that the conversion was aborted by a reset, ADCRH and ADCRL return to their reset states.

8.4.4.4 Power Control

The ADC module remains in its idle state until a conversion is initiated. If ADACK is selected as the conversion clock source, the ADACK clock generator is also enabled.

Power consumption when active can be reduced by setting ADLPC. This results in a lower maximum value for f_{ADCK} (see the electrical specifications).

8.4.4.5 Total Conversion Time

The total conversion time depends on the sample time (as determined by ADLSMP), the MCU bus frequency, the conversion mode (8-bit or 10-bit), and the frequency of the conversion clock (f_{ADCK}). After the module becomes active, sampling of the input begins. ADLSMP is used to select between short and long sample times. When sampling is complete, the converter is isolated from the input channel and a successive approximation algorithm is performed to determine the digital value of the analog signal. The

CPWMS	MSnB:MSnA	ELSnB:ELSnA	Mode	Configuration
Х	ХХ	00	Pin not used for revert to general	TPM channel; use as an external clock for the TPM or -purpose I/O
0	00	01	Input capture	Capture on rising edge only
		10		Capture on falling edge only
		11		Capture on rising or falling edge
	01 00 Output		Software compare only	
		01	compare	Toggle output on compare
		10		Clear output on compare
		11		Set output on compare
	1X	10	Edge-aligned	High-true pulses (clear output on compare)
		X1	PWM	Low-true pulses (set output on compare)
1	XX	10	Center-aligned	High-true pulses (clear output on compare-up)
		X1	PWM	Low-true pulses (set output on compare-up)

If the associated port pin is not stable for at least two bus clock cycles before changing to input capture mode, it is possible to get an unexpected indication of an edge trigger. Typically, a program would clear status flags after changing channel configuration bits and before enabling channel interrupts or using the status flags to avoid any unexpected behavior.

11.3.5 Timer Channel Value Registers (TPMxCnVH:TPMxCnVL)

These read/write registers contain the captured TPM counter value of the input capture function or the output compare value for the output compare or PWM functions. The channel value registers are cleared by reset.

_	7	6	5	4	3	2	1	0
R W	Bit 15	14	13	12	11	10	9	Bit 8
Reset	0	0	0	0	0	0	0	0



	7	6	5	4	3	2	1	0
R W	Bit 7	6	5	4	3	2	1	Bit 0
Reset	0	0	0	0	0	0	0	0

Figure 11-10. Timer Channel Value Register Low (TPMxCnVL)

In input capture mode, reading either byte (TPMxCnVH or TPMxCnVL) latches the contents of both bytes into a buffer where they remain latched until the other byte is read. This latching mechanism also resets (becomes unlatched) when the TPMxCnSC register is written.





¹ BDFR is writable only through serial background mode debug commands, not from user programs.

Figure 12-6. System Background Debug Force Reset Register (SBDFR)

Table 12-3. SBDFR Register Field Description

Field	Description
0 BDFR	Background Debug Force Reset — A serial active background mode command such as WRITE_BYTE allows an external debug host to force a target system reset. Writing 1 to this bit forces an MCU reset. This bit cannot be written from a user program.





Figure A-7. Typical High-Side Driver (Source) Characteristics High Drive (PTxDSn = 1), V_{DD} = 5.0 V, V_{OH} vs. I_{OH}



Figure A-8. Typical High-Side Driver (Source) Characteristics High Drive (PTxDSn = 1), V_{DD} = 3.0 V, V_{OH} vs. I_{OH}





Figure A-13. IRQ/KBIPx Timing

A.8.2 Timer/PWM (TPM) Module Timing

Synchronizer circuits determine the shortest input pulses that can be recognized or the fastest clock that can be used as the optional external source to the timer counter. These synchronizers operate from the current bus rate clock.

Function	Symbol	Min	Max	Unit
External clock frequency	f _{TCLK}	dc	f _{Bus} /4	MHz
External clock period	t _{TCLK}	4	_	t _{cyc}
External clock high time	t _{clkh}	1.5	_	t _{cyc}
External clock low time	t _{clkl}	1.5	_	t _{cyc}
Input capture pulse width	t _{ICPW}	1.5	_	t _{cyc}

Table A-9. TPM/MTIM Input Timing



Figure A-14. Timer External Clock



Figure A-15. Timer Input Capture Pulse